

Features

- High isolation 5000 VRMS
- Patented coplanar structure DMC-Isolator®
- Peak Breakdown Voltage
 - 250V CTM3031,CT3032,CT3033
 - 400V CTM3041,CT3042,CT3043
- Operating temperature range 55 °C to 100 °C
- External Creepage ≥ 5.0mm
- Distance Through Isolation ≥ 0.4mm
- Clearance Distance ≥ 5.0mm
- RoHS and REACH Compliance
- Halogen Free Compliance
- MSL class 1
- Regulatory Approvals
 - ✓ UL UL1577 (E364000)
 - ✓ VDE EN60747-5-5(VDE0884-5)
 - ✓ CQC GB4943.1, GB8898
 - ✓ IEC60065, IEC60950

Description

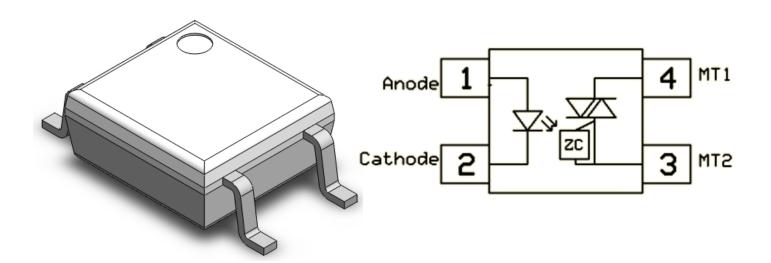
The CTM3031, CTM3032, CTM3033, CTM3041, CTM3042 and CTM3043 consists of a Zero Cross Photo Triac optically coupled to an Infrared-emitting diode in a 4-lead Mini-Flat DMC-Isolator® package.

Applications

- Motor Controls
- Lamp ballasts
- Static AC Power Switch
- Solenoid/ Valve Control

Package Outline

Schematic





Absolute Maximum Ratings $T_A = 25^{\circ}C$, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes	
Viso	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	3750	V _{RMS}		
Topr	Operating temperature		-55 ~ +100	°C	
Тѕтс	Storage temperature		-55 ~ +150	°C	
Tsol	Soldering temperature (For 10 seconds)		260	°C	
Emitter		,		1	
I _F	Forward current	60	60 mA		
I _{F(TRANS)}	Peak transient current (≤1µs P.W,300pps)	1	А		
V _R	Reverse voltage	6	V		
P _D	Power dissipation		100	mW	
Detector	r	,		1	
P _D	Power dissipation		300	mW	
		CTM3031,	0.50	.,	
V_{DRM}	Off-State Output Terminal Voltage	CT3032,CT3033	250	V	
		CTM3041,	400	.,	
		CT3042,CT3043	400	V	
I _{TSM}	Peak Repetitive Surge Current	1	А		



Electrical Characteristics $T_A = 25$ °C (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F =10mA	-	-	1.5	V	
I _R	Reverse Current	V _R = 6V	-	-	5	μΑ	
C _{IN}	Input Capacitance	f= 1MHz	-	45	-	pF	

Detector Characteristics

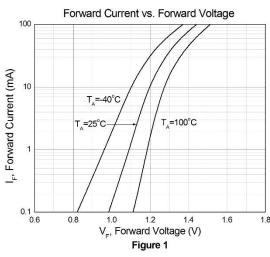
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
I _{DRM1}	Peak Blocking Current	I _F = 0mA, V _{DRM} = Rated V _{DRM}	-	-	100	nA	
I _{DRM2}	Inhibit Leakage Current	I _F = Rated I _F T, V _{DRM} = Rated V _{DRM}	-	-	500	μΑ	
V _{INH}	Inhibit Voltage	I _F = Rated I _{FT} ,	-	-	20	V	
Vтм	Peak On-State Voltage	I _F = Rated I _{FT} , I _{TM} = 100mA	-	-	3	V	
dv/dt	Critical Rate of Rise off-State Voltage	V _{PEAK} = Rated V _{DRM}	1000	-	-	V/μs	

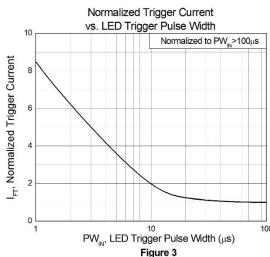
Transfer Characteristics

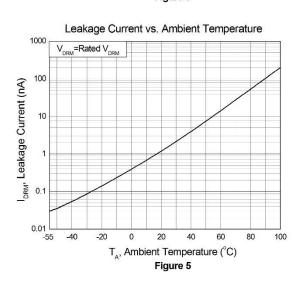
Symbol	Parameters		Test Conditions	Min	Тур	Мах	Units	Notes
	la must	CTM3031, CTM3041		-	-	15		
lft	Input Trigger Current	CTM3032, CTM3042	Terminal Voltage = 3V I _{TM} =100mA	-	ı	10	mA	
		CTM3033, CTM3043		-	1	5		
Ін	Holding Curre	ent	Terminal Voltage from "ON" to "OFF" "ON" state I _F =0mA	-	270	-	μΑ	
Rio	Isolation Res	istance	V _{IO} = 500V _{DC} , 40 ~ 60% R.H.	1x10 ¹¹	-	-	Ω	
Сю	Isolation Cap	acitance	f= 1MHz	-	0.25	-	pF	

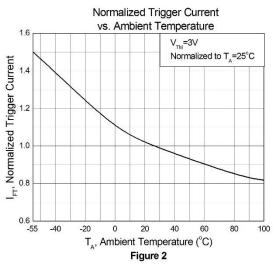


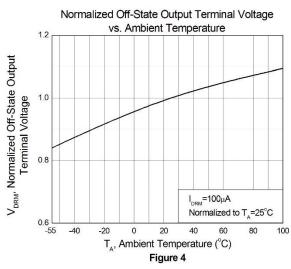
Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified

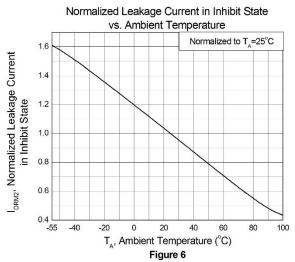






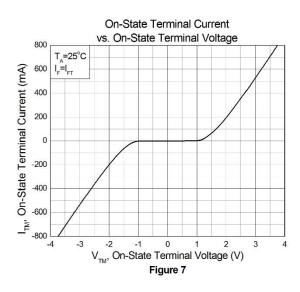


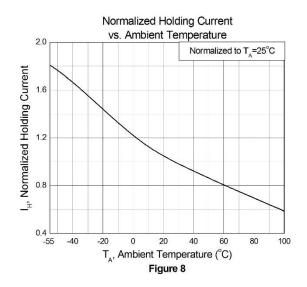


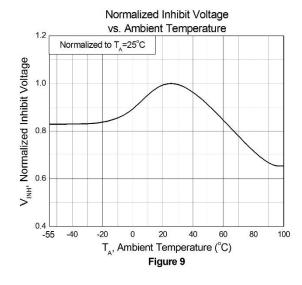




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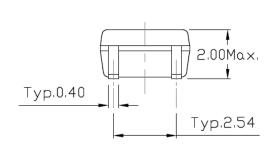


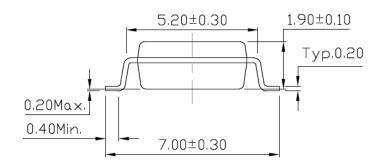


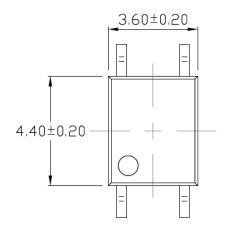


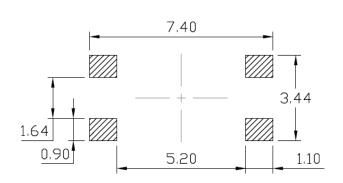


Package Dimension Dimensions in mm unless otherwise stated

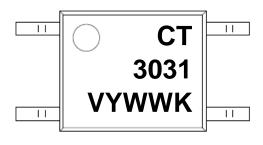








Marking Information



Note:

CT : Denotes "CT Micro"

3031 : Part Number

V : VDE Safety Mark Option (Blank or V)

Y : One Digit Year CodeWW : Two Digit Work WeekK : Manufacturing Code



Ordering Information

CTM303X(V)(Z)

CT = Denotes "CT Micro"

303X = Part No. (CT303X:0,1,2), (CT304X:0,1,2,3)

V = VDE Safety Mark Option (Blank or V)

Y = Lead Form Option (Blank, S, SL, M or SLM)

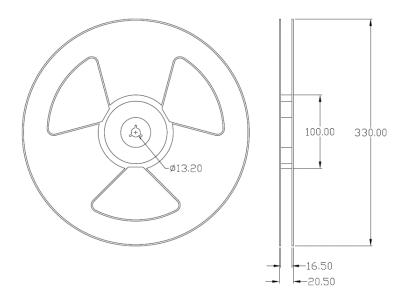
Z = Tape and Reel Option (Blank, T1, T2, T3 or T4)

G = Material Option (G: Halogen Free, Blank: Non-Halogen Free)

Option	Option Description	
T1	Surface Mount Lead Forming – With Option 1 Taping	3000 Units/Reel
T2	Surface Mount Lead Forming – With Option 2 Taping	3000 Units/Reel

Reel Dimension All dimensions are in mm, unless otherwise stated

Option T1/T2

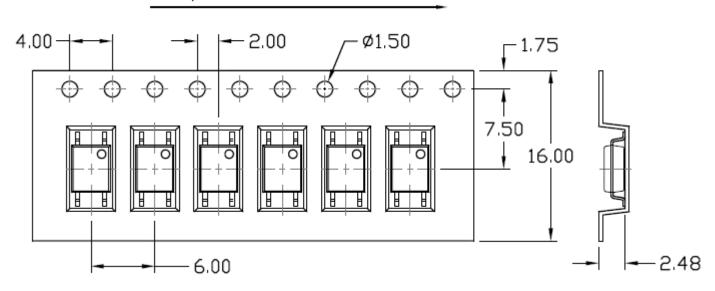




Carrier Tape Specifications Dimensions in mm unless otherwise stated

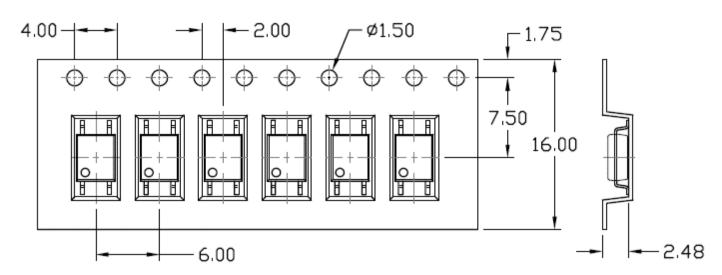
Option T1

Input Direction



Option T2

Input Direction



Solderability spec (Follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (Follow the JEDEC standard JESD22-A111)

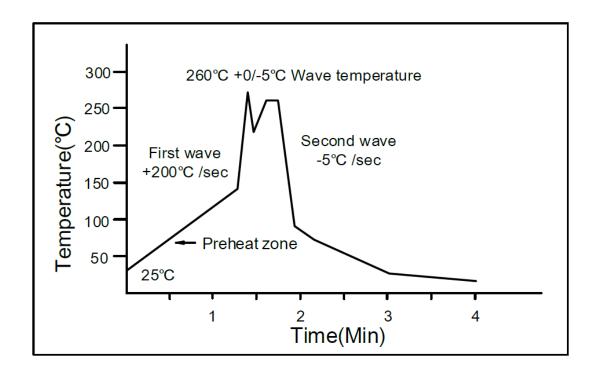
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature: 25 to 140°C.

Preheat time: 30 to 80 sec.



Iron soldering (Follow the standard MIL-STD 202G, Method 210F)

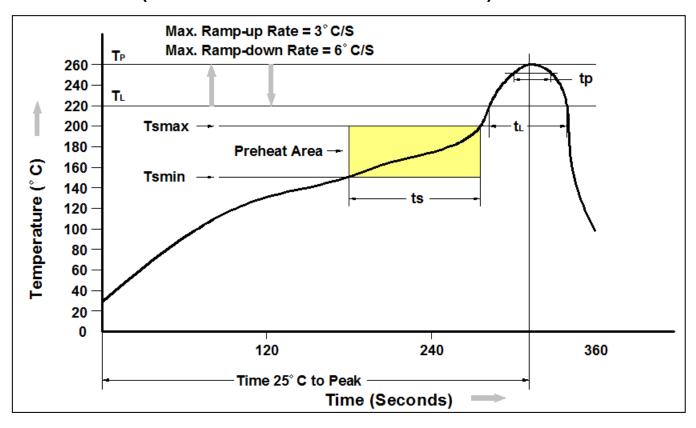
Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: 350±10°C

Time: 5 sec max.



Reflow Profile (Follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t₂)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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